



MTM POWER®

P r e s s e + + + P r e s s

Extreme Conditions Require Absolute Security

Through years of intensive research, MTM Power® has developed a worldwide unique potting technology: the **THERMOSELECTIVE VACUUM ENCAPSULATION**.

The target of this patented encapsulation technology (EP 1 987 708 / US Patent No. 8, 821, 778 B2) is the production of a "cemented joint", an absolutely permanent joint between the electronics and the potting resin. This technical innovation significantly increases the quality of MTM Power Modules. They are protected against mechanical stress, such as shock and vibration. Neither conductive dusts, moisture or condensation affect the devices. In addition, they have good temperature characteristics and a long life, just to name a few outstanding features that are unparalleled in the market.



Encl.: photo MTM_Thermoselective_Vacuum_Encapsulation.jpg

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